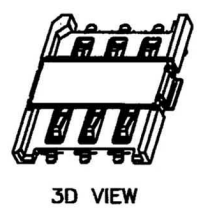
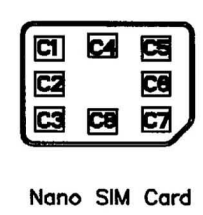
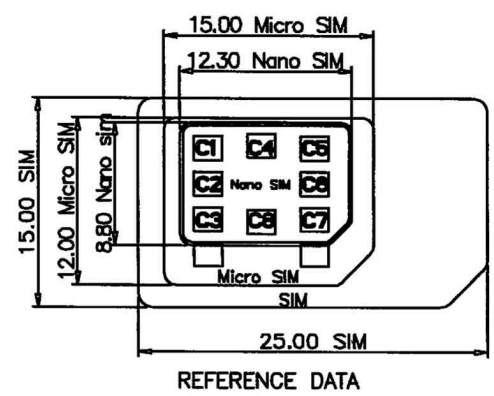


Notes:

- Material:
  - Plastic Housing: LCP 30%GF, UL94V-0, Black
  - Contact Terminal: Phosphor Bronze Thickness=0.15mm
  - Cover: SUS201-H, Thickness=0.15mm
- Plating:
  - Contact Terminal:
    - Contact Area: Part Number Rule
    - Solder area: G/F Gold
    - Underplating: Ni overall 50u" Min.
  - Cover:
    - Underplating: Ni overall 50u"
- Mechanical:
  - Life cycles: 5000.
- Electrical:
  - Voltage Rating: 30V AC RMS
  - Current Rating: 0.5A AC RMS Max
  - Operating Temperature: -20°C to +80°C
  - Dielectric Withstanding Voltage: 100V AC (60Sec Min)
  - Insulation Resistance: 100MΩ Min
  - Contact Resistance: 30mΩ Max

- C1 -----> VCC
- C2 -----> RST
- C3 -----> CLK
- C5 -----> GND
- C6 -----> Vpp
- C7 -----> I/O

RECOMMENDED PCB LAYOUT  
GENERAL TOLERANCE ±0.05



RoHS Compliant		玄茂科技股份有限公司 <b>HSUAN MAO TECHNOLOGY CO., LTD.</b>	
APPD. 核准		TOLERANCE 容許公差	PART NAME 品名
DWG. 製圖	SCALE 比例 參考	.0 ± 0.30 .00 ± 0.20 ANG. ± 3°	Nano SIM Card Connector 6Pin SMT Type Gold Flash Plating W/ Locating Peg & W/ Solder Tail Black Color Reel Packing ROHS
DATE 制表日	UNIT 單位 M M	SIZE. 紙張尺寸 A 4	PART NO.
2015/04/10	PAGE 張數 1 OF 1	REV. 版次 A	C0646-06DGYBR0R 料號